

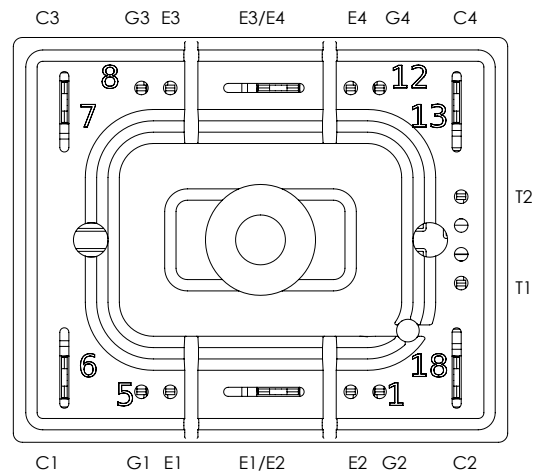
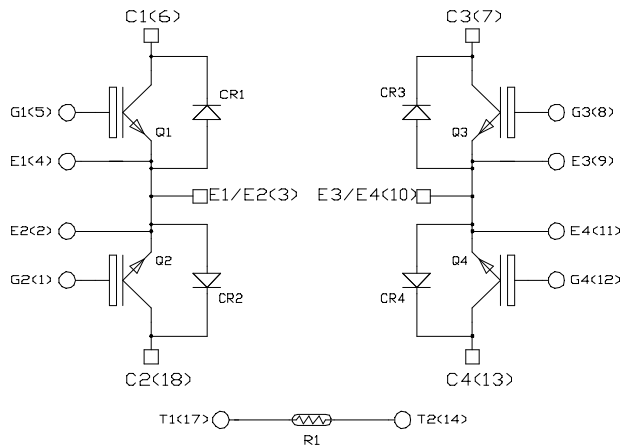
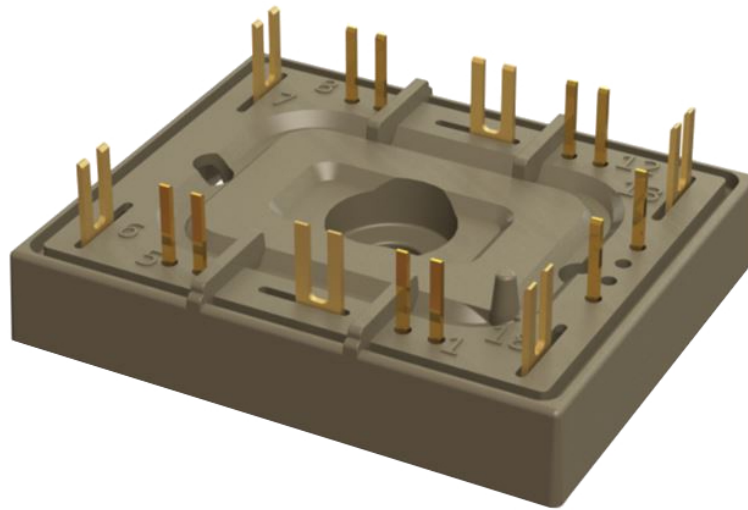


# MSCGLQ50DDU120CTBL2NG

## Double Dual Common Emitter High-Speed IGBT4 Power Module

### Product Overview

The MSCGLQ50DDU120CTBL2NG device is a 1200 V, 50 A double dual common emitter high-speed IGBT4 power module.



All ratings at  $T_j = 25^\circ\text{C}$ , unless otherwise specified.

**Caution:** These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

## Features

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The following are the key features of MSCGLQ50DDU120CTBL2NG device:

- High speed IGBT4
  - Low voltage drop
  - Low leakage current
  - Low switching losses
- SiC Schottky Diode
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature independent switching behavior
  - Positive temperature coefficient on VF
- Ultra low weight and profile
- Kelvin emitter for easy drive
- Si<sub>3</sub>N<sub>4</sub> substrate with thick copper for improved thermal performance
- Internal thermistor for temperature monitoring
- Extended temperature range

## Benefits

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The following are the benefits of MSCGLQ50DDU120CTBL2NG device:

- High efficiency converter
- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-heatsink thermal resistance
- Low profile
- RoHS Compliant
- Solderable terminals both for power and signal for easy PCB mounting
- Very integrated power conversion system

## Application

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The following are the applications of MSCGLQ50DDU120CTBL2NG device:

- High reliability power systems
- AC switches

### 1. Electrical Specifications

This section provides the electrical specifications of MSCGLQ50DDU120CTBL2NG device.

#### 1.1 IGBT4 Characteristics (Per IGBT)

The following table lists the absolute maximum ratings of MSCGLQ50DDU120CTBL2NG device.

**Table 1-1. Absolute Maximum Ratings**

Symbol	Parameter	Maximum Ratings	Unit	
$V_{CES}$	Collector-Emitter voltage	1200	V	
$I_C$	Continuous collector current	$T_H = 25^\circ\text{C}$	110	A
		$T_H = 100^\circ\text{C}$	50	
$I_{CM}$	Pulsed collector current	$T_H = 25^\circ\text{C}$	180	
$V_{GE}$	Gate-Emitter voltage	$\pm 20$	V	
$P_D$	Power dissipation	$T_H = 25^\circ\text{C}$	375	W

The following table lists the electrical characteristics of MSCGLQ50DDU120CTBL2NG device.

**Table 1-2. Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$I_{CES}$	Zero gate voltage collector current	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	—	—	25	$\mu\text{A}$	
$V_{CE(sat)}$	Collector emitter saturation voltage	$V_{GE} = 15\text{ V}$ $I_C = 50\text{ A}$	$T_J = 25^\circ\text{C}$	1.7	2.05	2.4	V
			$T_J = 150^\circ\text{C}$	—	2.6	—	
$V_{GE(th)}$	Gate threshold voltage	$V_{GE} = V_{CE}$ $I_C = 1.7\text{ mA}$	5.3	5.8	6.3	V	
$I_{GES}$	Gate-Emitter leakage current	$V_{GE} = 20\text{ V}$ $V_{CE} = 0\text{ V}$	—	—	150	nA	

The following table lists the dynamic characteristics of MSCGLQ50DDU120CTBL2NG device.

**Table 1-3. Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$C_{ies}$	Input capacitance	$V_{GE} = 0\text{ V}$	—	2770	—	pF	
$C_{oes}$	Output capacitance	$V_{CE} = 25\text{ V}$	—	185	—		
$C_{res}$	Reverse transfer capacitance	$f = 1\text{ MHz}$	—	160	—		
$Q_g$	Total gate charge	$V_{GE} = 15\text{ V}$ $V_{CE} = 960\text{ V}$ $I_C = 50\text{ A}$	—	230	—	nC	
$T_{d(on)}$	Turn-on delay time	$V_{GE} = \pm 15\text{ V}$	$T_J = 150^\circ\text{C}$	—	30	—	ns
$T_r$	Rise time	$V_{Bus} = 600\text{ V}$		—	49	—	
$T_{d(off)}$	Turn-off delay time	$I_C = 50\text{ A}$		—	366	—	
$T_f$	Fall time	$R_G = 10\ \Omega$		—	48	—	
$E_{on}$	Turn-on switching energy	$V_{GE} = \pm 15\text{ V}$ $V_{Bus} = 600\text{ V}$	$T_J = 150^\circ\text{C}$	—	2.8	—	mJ
$E_{off}$	Turn-off switching energy	$I_C = 50\text{ A}$ $R_G = 10\ \Omega$	$T_J = 150^\circ\text{C}$	—	2.8	—	
$R_G$	Integrated gate resistor		—	4	—	$\Omega$	
$I_{SC}$	Short circuit data	$V_{GE} \leq 15\text{ V}$ $V_{Bus} = 900\text{ V}$ $t_p \leq 10\ \mu\text{s}$	$T_J = 150^\circ\text{C}$	—	190	—	A
$R_{thJH}$	Junction-to-heatsink thermal resistance	$\lambda_{paste} = 3.4\text{ W/mK}$	—	0.4	—	$^\circ\text{C/W}$	

### 1.2 SiC Diode Ratings and Characteristics (Per SiC Diode)

The following table lists the SiC diode ratings and characteristics of MSCGLQ50DDU120CTBL2NG device.

**Table 1-4. SiC Diode Ratings and Characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$V_{RRM}$	Peak repetitive reverse voltage			—	—	1200	V
$I_{RM}$	Reverse leakage current	$V_R = 1200\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	—	10	200	$\mu\text{A}$
			$T_J = 175\text{ }^\circ\text{C}$	—	150	—	
$I_F$	DC forward current	—	$T_H = 100\text{ }^\circ\text{C}$	—	30	—	A
$V_F$	Diode forward voltage	$I_F = 30\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	—	1.5	1.8	V
			$T_J = 175\text{ }^\circ\text{C}$	—	2.1	—	
$Q_C$	Total capacitive charge	$V_R = 600\text{ V}$		—	130	—	nC
C	Total capacitance	$f = 1\text{ MHz}$ $V_R = 400\text{ V}$		—	141	—	pF
		$f = 1\text{ MHz}$ $V_R = 800\text{ V}$		—	105	—	
$R_{thJH}$	Junction-to-heatsink thermal resistance	$\lambda_{\text{paste}} = 3.4\text{ W/mK}$		—	0.854	—	$^\circ\text{C/W}$

### 1.3 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCGLQ50DDU120CTBL2NG device.

**Table 1-5. Thermal and Package Characteristics**

Symbol	Characteristic		Min	Typ	Max	Unit
$V_{ISOL}$	RMS isolation voltage, any terminal to case $t = 1\text{ min}$ , 50 Hz/60 Hz		2500	—	—	V
$T_J$	Operating junction temperature range		-55	—	175	$^\circ\text{C}$
$T_{JOP}$	Recommended junction temperature under switching conditions		-55	—	$T_{Jmax} - 25$	
$T_{STG}$	Storage case temperature		-55	—	125	
$T_C$	Operating case temperature		-55	—	125	
Torque	Mounting torque	To heatsink M4	1.5	—	2	
Wt	Package weight		—	21.5	—	g

# MSCGLQ50DDU120CTBL2NG

## Electrical Specifications

The following table lists the temperature sensor NTC of the MSCGLQ50DDU120CTBL2NG device.

**Table 1-6. Temperature Sensor NTC**

Symbol	Characteristic	Min	Typ	Max	Unit
R <sub>25</sub>	Resistance at 25 °C	—	50	—	kΩ
ΔR <sub>25</sub> /R <sub>25</sub>		—	5	—	%
B <sub>25/85</sub>	T <sub>25</sub> = 298.15 K	—	3952	—	K
ΔB/B	— T <sub>C</sub> = 100 °C	—	4	—	%

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

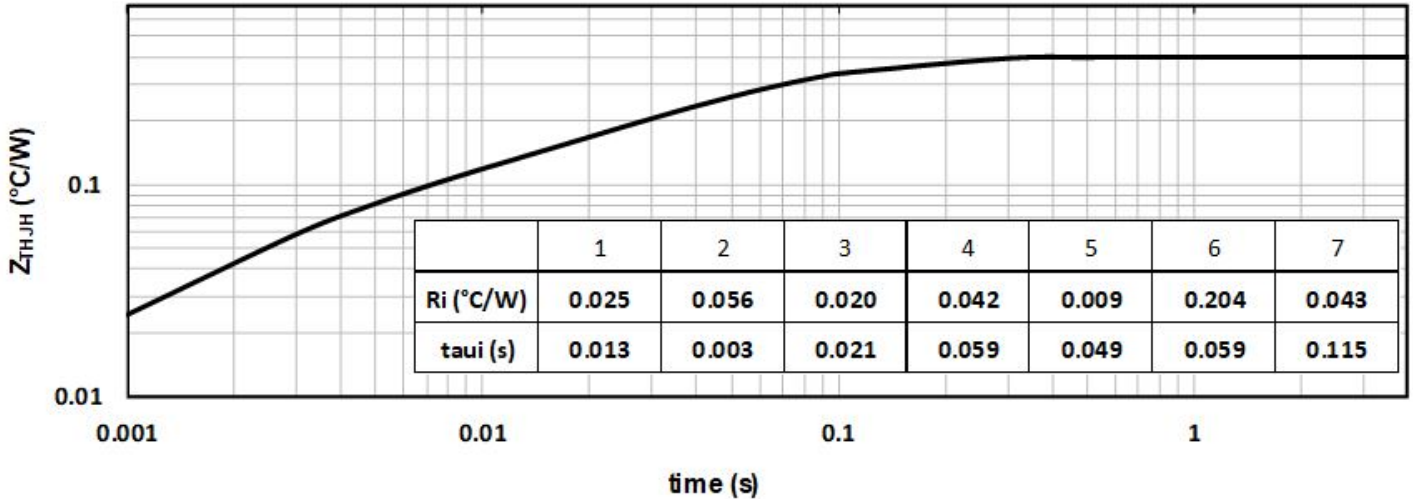
T: Thermistor temperature  
R<sub>T</sub>: Thermistor value at T

**Note:** See [APT0406—Using NTC Temperature Sensor Integrated into Power Module](#) for more information.

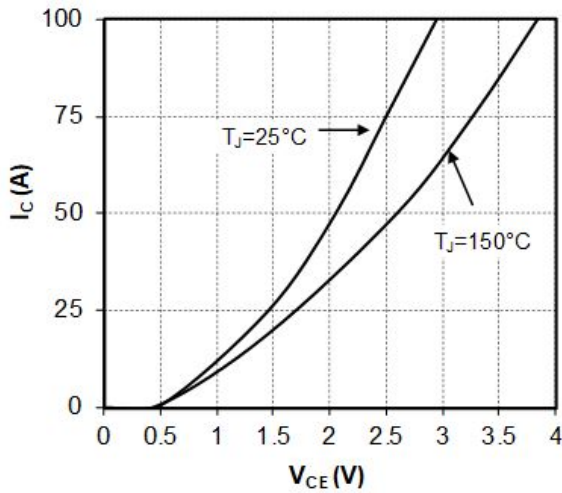
### 1.4 Typical IGBT 4 Performance Curve (Per IGBT)

This section shows the typical IGBT 4 performance curves of MSCGLQ50DDU120CTBL2NG device.

**Figure 1-1. Junction-to-Heatsink Thermal Impedance**



**Figure 1-2. Output Characteristics ( $V_{GE} = 15\text{ V}$ )**



**Figure 1-3. Output Characteristics**

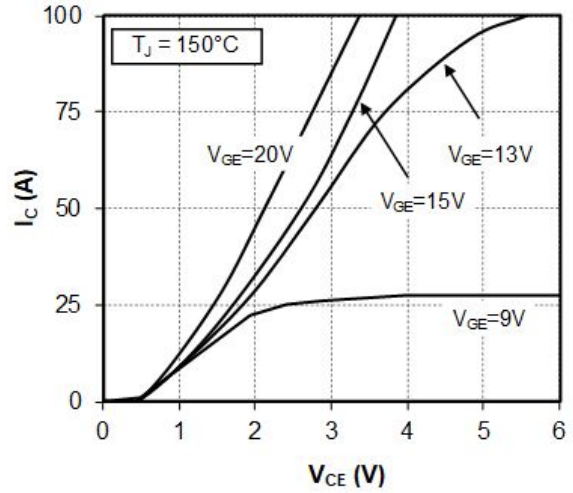


Figure 1-4. Transfer Characteristics

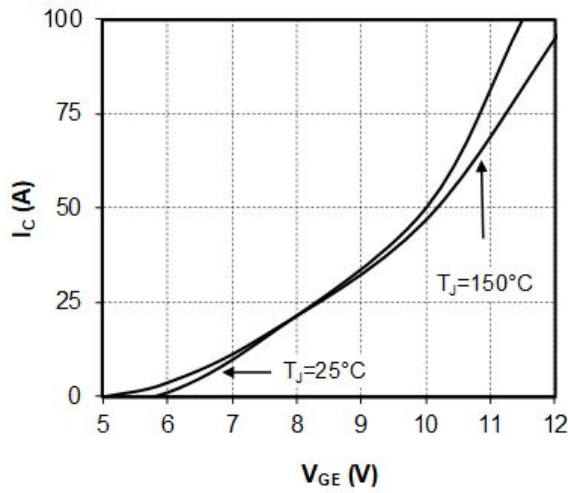


Figure 1-5. Energy Losses vs. Collector Current

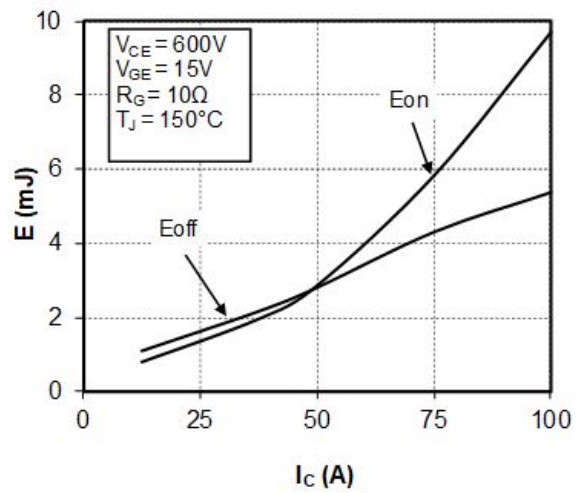


Figure 1-6. Switching Energy Losses vs. Gate Resistance

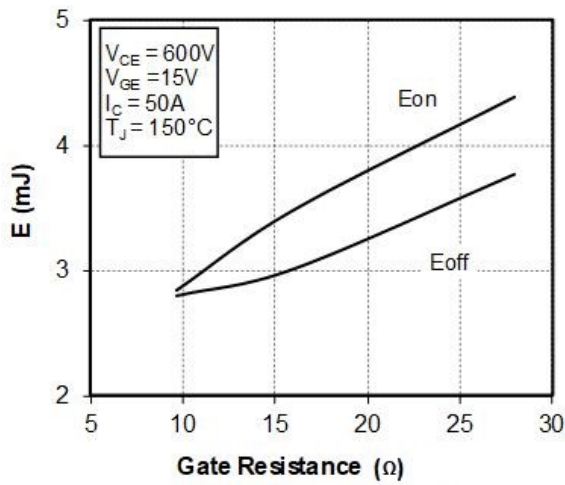
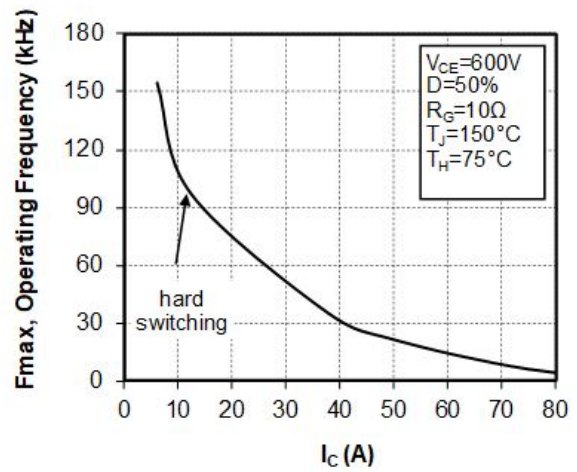


Figure 1-7. Operating Frequency vs. Collector Current

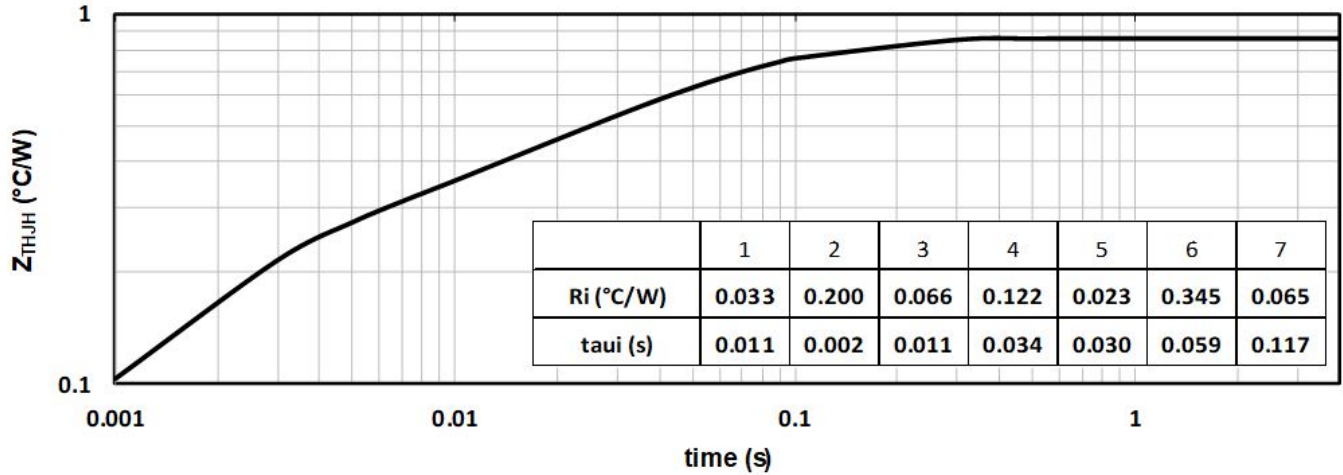




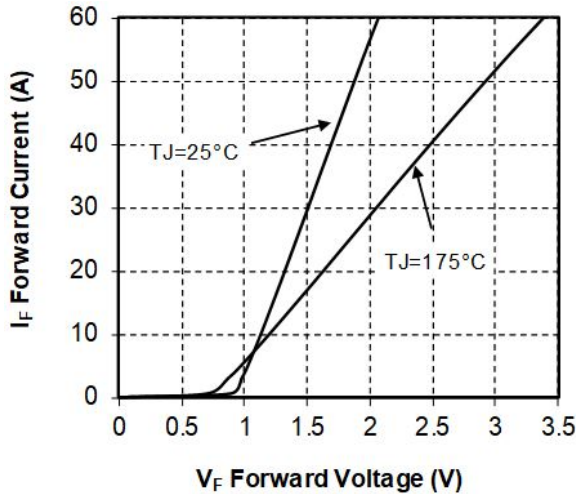
### 1.5 Typical SiC Diode Performance Curves (Per SiC Diode)

This section shows the typical SiC diode performance curves of MSCGLQ50DDU120CTBL2NG device.

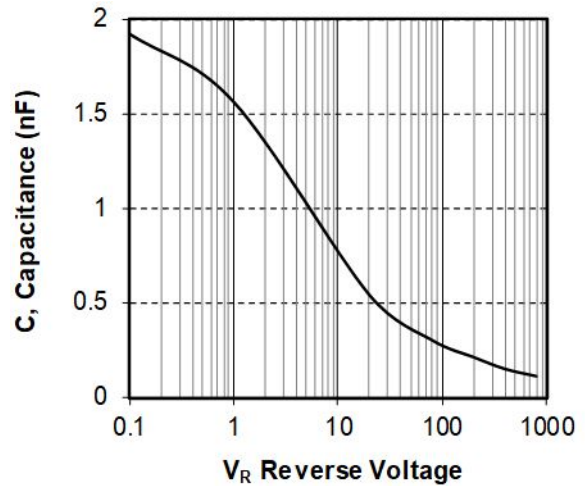
**Figure 1-8. Junction-to-Heatsink Thermal Impedance**



**Figure 1-9. Forward Characteristics**



**Figure 1-10. Capacitance vs. Reverse Voltage**



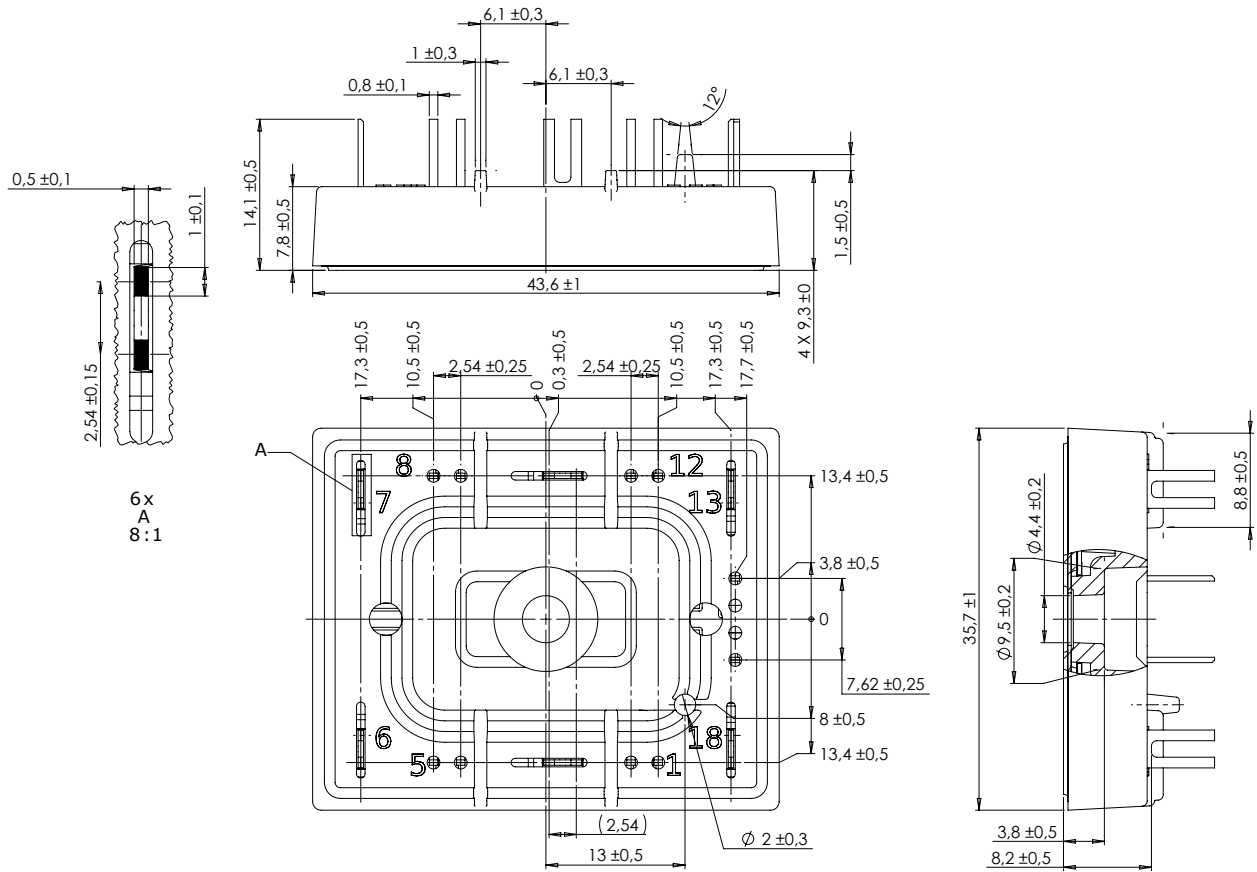
### 2. Package Specifications

The following section shows the package specification of MSCGLQ50DDU120CTBL2NG device.

#### 2.1 Package Outline

The following figure shows the package outline drawing of MSCGLQ50DDU120CTBL2NG device. The dimensions in the following figure are in millimeters.

**Figure 2-1. Package Outline Drawing**



### 3. Revision History

Revision	Date	Description
A	07/2021	Initial Revision

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